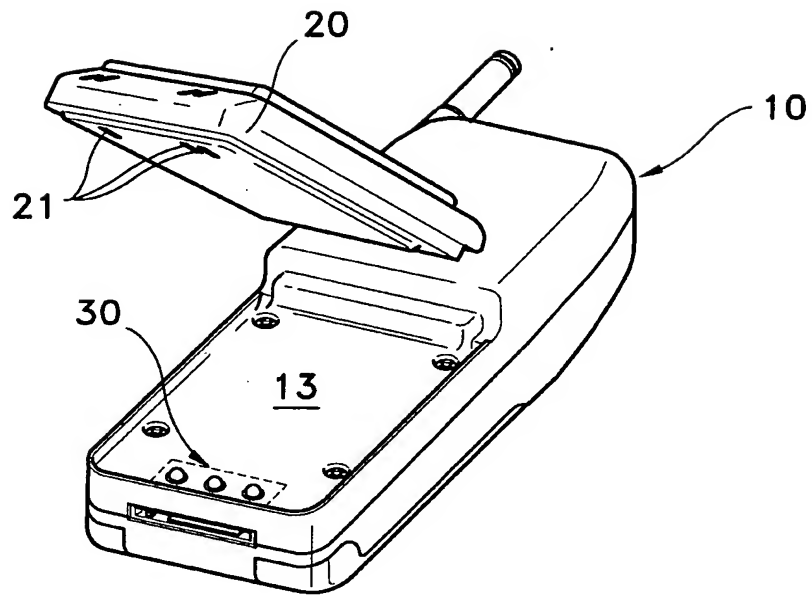
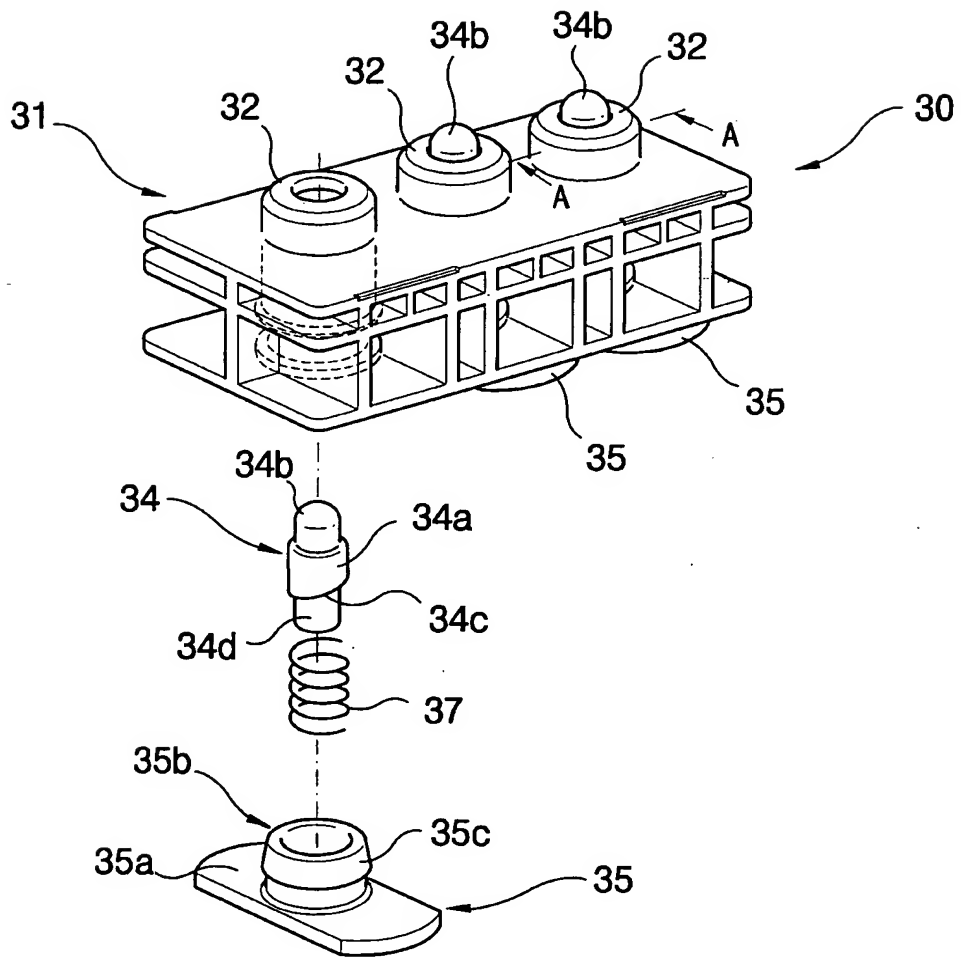


FIG. 1



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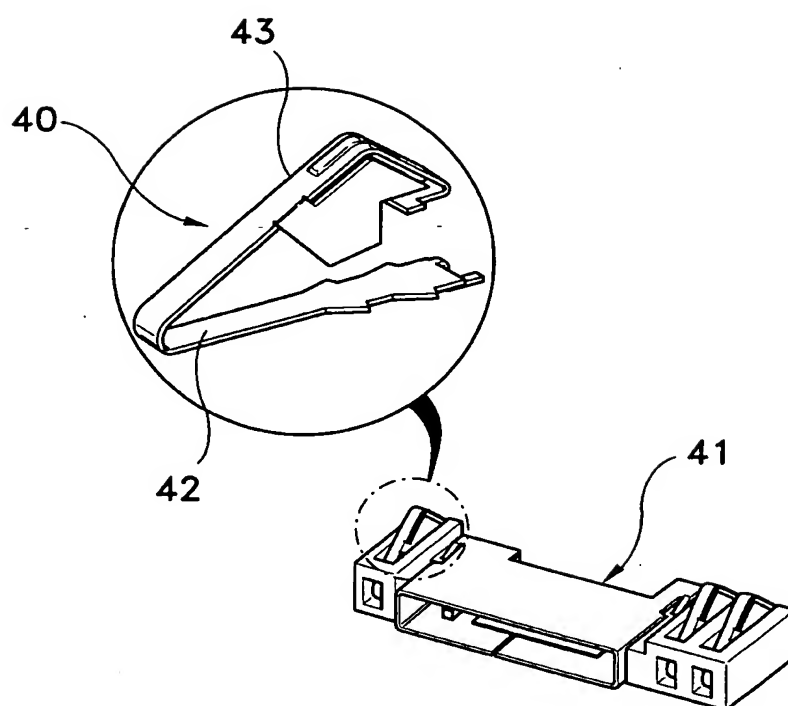
FIG. 2



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This cross-sectional view illustrates a semiconductor device. A central structure 34, featuring a rounded top 34b, is positioned within a central opening of a layer 32. The layer 32 is composed of multiple stacked layers, including 32a, 32b, 32c, and 32d. The device is mounted on a substrate 11. Various layers and components are labeled with reference numerals: 10, 30, 31, 32, 32a, 32b, 32c, 32d, 34, 34a, 34b, 34c, 35, 35a, 35b, 35c, 37, and 11.

FIG. 4



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